

## ABSTRACT

The present invention provides a wafer double-side polishing apparatus comprising at least a carrier plate having wafer holding holes; upper and lower turn tables to which polishing pads are attached; and a slurry supply means; with wafers held in the wafer holding holes, the carrier plate being moved between the upper and lower turn tables while supplying slurry, to simultaneously polish both front and back surfaces of wafers, wherein a PCD of upper turn table load supporting points that is a diameter of a circle joining load supporting points of the upper turn table coincides with a PCD of centers of the wafer holding holes on the carrier plate that is a diameter of a circle joining each center of the wafer holding holes on the carrier plate. Thereby, there can be provided a wafer double-side polishing apparatus and method in which it is possible to control wafer shape by deforming turn tables with excellent responsiveness, and to polish the wafers stably with high precision without deteriorating wafer shape.